



Attorney's Docket No.: 07402-039001

*SA  
Chun  
7-25-01*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Carlson, et al. Art Unit : 2815  
Serial No.: 09/547,061 Examiner : Lourdes Cruz  
Filed : April 7, 2000  
Title : INSULATOR/METAL BONDING ISLAND FOR ACTIVE AREA  
SILVER EPOXY BONDING

Commissioner for Patents  
Washington, D.C. 20231

RESPONSE

In response to the action mailed March 15, 2001, please  
amend the application as follows:

In the claims:

\ Please amend claims 1, 9, and 13 as follows:

-- 1. (Amended) A semiconductor interconnection system,  
comprising:  
a semiconductor die;  
first and second conductive contacts, said first  
conductive contact coupled to a surface of said semiconductor  
die, and said second conductive contact coupled to an external  
structure;  
a silver epoxy bond interposed between said first and  
second conductive contacts, said epoxy bond providing electrical

*Sub  
B1  
A1*

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being  
deposited with the United States Postal Service as first class mail with  
sufficient postage on the date indicated below and is addressed to the  
Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit

Signature

Debbrah K. Sim

Typed or Printed Name of Person Signing Certificate

TECHNOLOGY CENTER 2800

JUL 23 2001

RECEIVED